| | 11.5 | Denartr | nent of Commerce | e Datent and | Trademark Office | Docket No.: | | Serial | No.: | |
|---------------------|----------|----------------|--------------------|-------------------------------|---|--------------------------------------|----------------|---------------|---------------|--------|
| | 0.5. | Б ерш и | ment of Commerce | c, ratem and | Hademar Office | 6353/P1/DSM/L0 | ow k/jw | | 10/759,80 | ı |
| 10 | E J | ST OF | RELEVANT AR | T CITED BY | APPLICANT | Applicant(s): | _ | | | |
| (O, | | | (Use several she | | | Howard Li, et al | L | | | |
| FEB 0 | 3 2004 | | | | | Filing Date: Group: 1762 | | | | |
| • | المار | Ž | | • | | January 16, | 2004 | | Unknown | ر ه |
| | U.S. Pat | ont Do | | | | | | | | |
| • | | T DOG | | r . | , | | | | | |
| Exan Init | | | Document Number | Issue Date | Name | Class | Subcl | ass | Filing D | |
| 1/4 | 8 | AA | 3,156,073 | 11/10/64 | Strasbaugh | 451 | 16 | \mathcal{L} | _ | |
| | | AB | 3,564,776 | 02/23/71 | Aspden | 951 | 4 | | | |
| | | AC | 3,691,694 | 09/19/72 | Goetz et al. | 457 | 28 | 3 | | |
| | | AD | 3,603,042 | 09/07/71 | Boettcher | 451 | 26 | 9 | | |
| | | AE | 3,693,301 | 09/26/72 | Lemaitre | 451 | SS | | | |
| | | AF | 5,427,878 | 06/27/95 | Corliss | 430 | 30 | | | |
| | | AG | 6,051,113 | 04/18/00 | Moslehi | W | 192 | ./2 | | |
| | | AH | 6,086,734 | 07/11/00 | Harada | 204 | 298 | ,03 | | |
| | | ΑI | 6,120,641 | 09/19/00 | Stevens et al. | 156 | 345 | .22 | | |
| | | AJ | 6,143,126 | 11/07/00 | Stevens | 156 | 345 | 22 | | |
| 1 | 1 | AK | 6,166,801 | 12/26/00 | Dishon et al. | 355 | 27 | | | |
|] | Foreign | Patent l | Documents | | | | - - | | Trans | ation |
| | <u></u> | | Document Number | Date | Country | Class | Subcl | ass | Yes | No |
| 4/12 | X | AL | 61164773A2 | 07/25/86 | Japan | | | | Abstract Only | |
| 100 | | AM | 61188071A | 08/21/86 | Japan | | | | Abstract Only | |
| | | AN | 61244460 | 10/30/86 | Japan | | | | Abstract Only | |
| | | AO | 61265262A | 11/25/86 | Japan | | | | Abstract Only | |
| | 1 | AP | 63256342A2 | 10/24/88 | Јарал | | | | Abstract Only | |
| | THER | ART (| Including Author, | Title, Date, | Pertinent Pages, Etc.) | | | | | - |
| 4/2 | | AR | IBM Technical D | isclosure Bu | lletin: "Dry Point Detection Sy | stem," Dec. 1976, | pp. 2507- | 2509 | ···· | |
| " [| | AS | IBM Technical D | isclosure Bu | lletin: "Making Tunnel Barrier | Layers by Plasma | Deposition | n," Aug | g. 1979, p. | 1194 |
| | | | IBM Technical D | | lletin: "Apparatus for Locating | Particles on a Bla | nk Wafer | in a Sca | nning Elec | ctron |
| Examiner | Mir | 14 | an. | Date Conside | ered /23/6 | | | | - · · - | |
| EXAMI in conform | mancé a | nitial if | reference conside | red, whether de copy of th | or not citation is in conforman is form with your communicati | ce with MPEP 609 on to applicant. | ; Draw lin | e throu | gh citation | if not |
| | \sim | | | | | | | | | |

C:\WP51\FORMS\1449.PTO 1/94

| | U.S. | Depart | ment of Commerc | e, Patent and | Trademark Office | Docket No.: | | Serial No.: | |
|---------------------------------------|----------|-----------|--------------------------------|----------------|----------------------------------|--------------------|--------------|------------------|------------------------|
| | E | | | | | 6353/P1/DSM/L0 |)W K/JW | 10/759 | ,801 |
| 6 | | B) OF | RELEVANT AR | T CITED BY | / APPLICANT | Applicant(s): | | | |
| 553 | 0 3. 20 | X | (Use several she | eets if necess | ary) | Howard Li, et al | | | |
| 1 | | . | | | | Filing Date: | | Group: | 763 |
| · PRINT | TO TRUS | *** | | | | January 16, | 2004 | Unkn | wa. |
| 1 | U.S. Pat | ent Doc | uments | | | | | | |
| *Exan | | | Document Number | Issue Date | Name | Class | Subcl | | g Date If propriate |
| -A | 8 | AA | 5,655,110 | 08/05/97 | Krivokapic et al. | 716 | 19 | | |
| \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | 1 | AB | 5,657,254 | 08/12/97 | Sierk et al. | 702 | $\dot{\phi}$ | | |
| | 1 | AC | 5,866,437 | 02/02/99 | Chen et al. | 1/28 | iU | | |
| | | AD | 5,917,919 | 06/29/99 | Rosenthal | 381 | 71. | 7 | |
| | | AE | 5,926,690 | 07/20/99 | Toprac et al. | 429 | 17 | | |
| | <u> </u> | AF | 6,161,054 | 12/12/00 | Rosenthal et al. | 7711) | 121 | | |
| | | AG | 6,197,604 B1 | 03/06/01 | Miller et al. | 438 | 14 | | |
| | | AH | 6,208,751 B1 | 03/27/01 | Almogy | 282 | 149 | | |
| | | ΙA | 6,230,069 B1 | 05/08/01 | Campbell et al. | 711) | 121 | | |
| | | AJ | 6,245,581 B1 | 06/12/01 | Bonser et al. | 438 | 8 | | |
| \ | V | AK | 6,284,622 B1 | 09/04/01 | Campbell et al. | 438 | 424 | 7 | |
| I | Foreign | Patent I | Documents | | | | - | Tra | slation |
| | | | Document Number | Date | Country | Class | Subcl | ass Yes | No |
| 11 | Y | AL | 3142929A2 | 06/18/91 | Japan | | | Abstract | Daly |
| W. | · | AM | 4217456 | 08/07/92 | Japan | | - | Abstract | Only |
| | | AN | 569311A | 03/23/93 | Japan | | | Abstract | Only |
| | | AO | 639704A | 02/15/94 | Japan | | | Abstract | Ondy |
| | i | AP | WO 98/02910 | 01/22/98 | PCT | | | | |
| | OTHER | ART (| | | Pertinent Pages, Etc.) | | | <u>+</u> | |
| (1) | 7 | | IBM Technical D | isclosure Bul | letin: "Auto-Defect Detection/ | Visual Defect Rev | iew Inspec | tion System," | Feb. 1989, |
| \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | | | | isclosure Bul | letin: "Dual Microscope Semic | onductor Wafer Ir | spection N | lachine," Mar | ch 1989, |
| | | | pp. 474-479 IBM Technical D | isclosure Pul | letin: "Integrated Semiconduct | or Processing Easi | litation by | Mobile Ion G | ttering |
| \ | // \ | | During and After | Resist Strip," | May 1989, pp. 295-297 | or reocessing raci | manon by | ratonile toli O | ~~~~ |
| Examiner | MM | | · · | Date Conside | ered 123 6 | | | | |
| *EXAMI | NER: I | ntipal if | reference consider | red, whether | or not citation is in conformanc | e with MPEP 609; | Draw line | through citation | n if not in |
| conforma | nce and | μοήςοι | s i dered. Include o | opy of this f | orm with your communication t | o applicant. | | - | |
| C:\WP51\FC | RMS\144 | 19.PTO 1 | /94 | | | | | | |

| | U.S | . Depart | ment of Commerc | e, Patent and | Trademark Office | Docket No.: 6353/P1/DSM/L | ow k/Jw | Seria | 1 No.: 10/759,80 |)1 |
|--------|-------------------|--------------------|--------------------------------------|----------------|--|-------------------------------|---------------|----------|---------------------|----------------|
| 6 | PEV | eist of B | RELEVANT AR (Use several sho | | | Applicant(s): Howard Li, et a | J. | <u> </u> | | |
| | EB 0'9 | rā _{rš} . | | | | Filing Date: January 16, | | Grou | p: 7 | 763 A |
| | U.S. Pa | itent Doc | cuments | <u> </u> | | | <u> </u> | | | |
| | kaminer nitial | | Document Number | Issue Date | Name | Class | Subcl | lass | Filing l | Date If priate |
| , | 1 | AA | 6,368,879 B1 | 04/09/02 | Toprac | 438 | 5 | | | |
| | 1 | AB | 6,388,253 B1 | 05/14/02 | Su | 250 | 3/0 |) | | |
| | | AC | 6,405,096 B1 | 06/11/02 | Toprac et al. | 700 | 121 | | | |
| | | AD | 6,438,440 B1 | 08/20/02 | Hayashi | 700 | 121 | | | |
| | W | AE | 6,445,969 B1 | 09/03/02 | Kenney et al. | 700 | 108 | | | |
| | | AF | | | | | | - | Ţ | |
| | | AG | | | | | | | | |
| | | AH | | | · | | | | | |
| | | AI | | | | | | | | |
| | | AJ | | | | | | | | |
| | | AK | | | | | | | | |
| | Foreign | Patent | Documents | - | | | | | Transla | ation |
| | - 0 | | Document Number | Date | Country | Class | Subcl | lass | Yes | No |
| i | | AL | WO 99/49500 | 09/30/99 | PCT | | | | | |
| | 1 | AM | WO 99/59190 | 11/18/99 | PCT | | | | | |
| | | AN | WO 99/60614 | 11/25/99 | PCT | | | | | |
| | | AO | 1 052 060 A2 | 11/15/00 | Europe | | | | | |
| | V | AP | WO 00/57127 | 09/28/00 | PCT | | | | | |
| | OTHE | R ART (| Including Author, | Title, Date, | Pertinent Pages, Etc.) | | | | | |
| 1 | A. | | IBM Technical D 417-424 | isclosure Bu | lletin: "Automated Multiple | Angle of Incidence | Ellipsomete | r Syste | m," Feb. 1 | 990, pp |
| | | | Advanced via Ins | pection Tool | lletin: "Multiprocessor and M s," May 1992, pp. 190-191 | | | | | |
| | | AT | The Novascan 21 http://www.nova.o | | d On-Line Thickness Monitor | ing System for CM | P Application | ons", do | ownloaded | from |
| Exami | ner | XCI | | Date Consid | | | | | | |
| *EXA | MINER: | Initial if | eference conside | red, whether | or not citation is in conforma | nce with MPEP 609 | ; Draw line | throug | h citation | if not in |
| confor | mance and | not don b | nsideréd. Include i | copy of this t | form with your communication | n to applicant. | | | | |

C:\WP51\FORMS\1449.PTO 1/94
Express Mail Label No.: EL975550394US

| 6353/P1/DSM/LOW K/JW 10/759,801 | Docket No.: | Serial No.: |
|---------------------------------|----------------------|-------------|
| | 6353/P1/DSM/LOW K/JW | 10/759,801 |

ST OF RELEVANT ART CITED BY APPLICANT
(Use several sheets if necessary)

Applicant(s):
Howard Li, et al.

Filing Date: Group: Group: Unknown

U.S. Patent Documents

| Examiner Initial | | Document Number | Issue Date | Name | Class | Subclass | Filing Date I: Appropriate |
|---------------------|----|--------------------|---------------|------|-------|----------|-------------------------------|
| | AA | | | | | | |
| | AB | | | | | | |
| | AC | | | , | | | |
| | AD | | | | | | |
| | AE | | | | | | |
| | AF | | | | | | |
| | AG | | | | | | |
| | AH | | | | | | |
| | ΑĪ | | | | | , | |
| | AJ | | | | | | |
| | AK | | | | | | |

| _ | | | Document Number | Date | Country | Class | Subclass | Yes | No |
|---|------------|----|--------------------|----------|---------|-------|----------|-----|----|
| | <i>b</i> ^ | AL | EP 0 932 194 A1 | 07/28/99 | | | | | |
| | 10 | AM | WO 00/79355 A1 | 12/28/00 | | | | | |
| | he | AN | WO 02/04886 A1 | 01/17/02 | | | | | |
| | 10 | AO | · | | | | | | |
| | | AP | | | | | | | |

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

| | e | AR | J. Bruchez et al., "Linking European Suppliers with Global Users," Semiconductor International, March 1998 |
|------|-------|----|--|
| 1 | 4 | AS | J. Baliga, "MES and CIM: At the Center of Productivity," Semiconductor International, July 1998 |
| | M | AT | A. Braun, "Inspection, Measurement & Test," Semiconductor International, August 1998 |
| amir | ner A | | Data Considered |

10/2

*EXAMINER\ Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

C:\WP51\FORMS\1449.PTO 1/94

| Sheet <u>5 of 10</u> | <u>sheet</u> | <u> </u> | | | | | | | | |
|---------------------------------------|--------------|---------------------------------------|--|--|------------------------------|--|--------------|-------------------|-------------|--------------|
| U.S. | Departr | ment of Commerc | e, Patent and | Trademark O | ffice | Docket No.: | | Serial | | |
| (5) | | | | | | 6353/P1/DSM/L | OM K\1M |] l | 10/759,80 | 1 |
| \\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ | T OF | RELEVANT AR | | | Γ | Applicant(s): | | - | | |
| - 32 75% | 割 | (Use several sh | eets if necess | ary) | | Howard Li, et a | 1. | | | |
| EB 0. | 5 | | | | | Filing Date: | | Group | : 17 | 63 |
| Con a result | | | | | · · · · | January 16, | 2004 | | Unknowt |) |
| U.S. Par | tent Do | cuments | | | | | | | | |
| *Examiner | | Document | Issue | Ţ | | | Ī | | Filing I | |
| Initial | | Number | Date | | ame | Class | Subcl | ass | Appro | priate |
| | AA | | | ļ | | | | | | |
| | AB | · · · · · · · · · · · · · · · · · · · | | | | | <u> </u> | \longrightarrow | | |
| | AC | | | ļ | | | | | | |
| | AD | | | ļ | | | | | | |
| | AE | | | | | - | | \longrightarrow | | |
| | AF AG | | | <u> </u> | | | | | | |
| | AH | | <u> </u> | - | | | | | | |
| | Al | | | | | | | | | |
| | AJ | | | | | | | | | |
| • | AK | | | | | | | | | |
| Foreign | <u> </u> | I Documents | <u>. </u> | <u>. </u> | | _1 | <u> </u> | | Trans | lation |
| | <u> </u> | Document | T | | | 1 | T | | | |
| ì | | Number | Date | Co | untry | Class | Subcl | ass | Yes | Йo |
| | AL | | | | | | | | | |
| | AM | | | | | | | | | |
| | AN | | - | | | | | | | |
| | AO | | | | | | | | | |
| | AP | | | | | | | | | |
| OTHER | ART (| Including Author | , Title, Date, | Pertinent Page | es, Etc.) | | | | | |
| Na- | | | | | | laterials Unveils its | | | | |
| 100 | AS | Applied Material | s Press Relea | se Archive 19 | vww.appnedm 98 "Applied M | aterials.com/newsro laterials Announced | First Proce | ss Sequ | ence Inte | 2 gration |
| M | | Product: The Co 00169.html on 3/ | pper Intercor | nect ESS," do | wnloaded fror | n http://www.applied | lmaterials. | com/new | vsroom/pi | ŗ - |
| 1/2 | | | | Strategically: | Beyond Tradit | ional MES," Semico | nductor In | ternation | nal, Janua | ry 1999 |
| Examiner | | <u> </u> | Date Consid | ered | 31. | | | | | |
| +EYAMDIED I | | Toronco conside | read whather | | 77 1 | ance with MPEP 60 | 0. Dec. !- | a sh | L ale_a! | 16 |
| | | | | | | ance with MPEP 60 ation to applicant. | y, Draw iin | e uroug | gn citation | ı II not |
| C:\WP51\FORMS\14 Express Mail Lab | | | S | | | | | | | |

| U.S | . Departn | nent of Commerc | e, Patent and | Trademark Office | | Docket No.: 6353/P1/DSM/LC |)W K/JW | Serial | No.: 10/759,80 | 1 |
|----------------------|------------|---------------------------------|---------------------------------------|--|------------|---|---|-------------|-------------------|--------|
| (0` | | RELEVANT AR (Use several sho | | | | Applicant(s): Howard Li, et al | | - | | |
| FB 03 20 | Narge. | | | | | Filing Date: January 16, 2 | 2004 | Grou | p: 170 Unknown | 63 |
| U.S. Pa | atent Doc | uments | | | | ··· • — - · · · · · · · · · · · | | | | |
| *Examiner Initial | | Document Number | Issue Date | Name | | Class | Subci | ass | Filing I Appro | |
| | AA | | | | | | | | | |
| | AB AC | | | | | | | | | |
| | AD | <u> </u> | · · · · · · · · · · · · · · · · · · · | | | | - · · · · · · · · · · · · · · · · · · · | | | |
| | AE | | | | | | | · · · | | |
| | AF | | | | | | | | | |
| | AG | | | | | | | • | | |
| | AH | | | | | | | | | |
| | AI | | | | | | | | | |
| | AJ | | | | · | | | | | |
| | AK | | | | | | | | | |
| Foreig | n Patent I | Documents | | | | | | | Trans | lation |
| | | Document Number | Date | Country | , | Class | Subcl | ass | Yes | No |
| | AL | | | | | | | | | |
| | AM | | | | | · · | | | | |
| | AN | | | | | | | | | |
| | AO | | | | | | | | | |
| | AP | | L | | | | L | | <u> </u> | |
| OTHE | R ART (I | ncluding Author, | Title, Date, | Pertinent Pages, Etc | c.) | | | | | |
| 112 | AR | J. Bruchez et al., | "European S | uppliers Focusing o | n Tool P | roductivity," Semico | nductor In | ternatio | nal, April | 1999 |
| 7 | AS | J. Baliga, "Advar | ced Process | Control: Soon to b | e A Must | ," Semiconductor Int | ternational | , July 1 | 999 | |
| i~ | AT | J. Baliga, "How A | | | ctor Inter | national, July 1999 | | | | |
| tamiñer | 5 | | Date Conside | | 23 | ß | | | | |
| | | | | or not citation is in is form with your c | | ánce with MPEP 609 ation to applicant. | ; Draw lir | e throu | gh citation | if not |

Sheet 6 of 10 sheets

C:\WP51\FORMS\1449.PTO 1/94
Express Mail Label No.: EL975550394US

AS T. Zavecz et al., "Life Beyond Mix-and-Match: Controlling Sub-0.18 um Overlay Errors", Semiconductor International, July 2000

AT F. Poag et al., "Implementing on-line ADC and an Automated Yield Information Management System,"

F. Poag et al., "Implementing on-line ADC and an Automated Yield Information Management System,"

MICROmagazine.com, July, 2000

23

/ Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

C:\WP51\FORMS\1449.PTO 1/94

Examiner

| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc | OTHER ART | (Including | Author. | Title. | Date. | Pertinent | Pages. | Etc. |
|--|-----------|------------|---------|--------|-------|-----------|--------|------|
|--|-----------|------------|---------|--------|-------|-----------|--------|------|

AR A. Toprac et al., "Run-to-Run Control of Shallow Trench Isolation Etch," AEC/APC 2000

AS N. Patel, "Mix Issues in Process Control," Sematech AEC/APC Symposium XII, September 25, 2000

AT J. Holden et al., "Characterizing a CVD-Integrated Metrology System," Semiconductor International, October 2000

Examiner Date Considered

*EXAMINER: Infial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

C:\WP51\FORMS\1449.PTO \#94

| 105 | | | | Trademark Office | Docket No.: 6353/P1/DSM/L | .ow k/Jw | Serial No.: 10/759, | BO1 |
|----------------------|------------|---------------------------------|---------------|---|--|---------------------------|------------------------|-------------|
| O 1 2 2 | • | RELEVANT AR (Use several sh | | | Applicant(s): Howard Li, et a | al. | | |
| TA TRAD | Chi.P.T. | | | | Filing Date: January 16 | , 2004 | Group: Unkno | 63 |
| | atent Doc | uments | | | · <u></u> | | | |
| *Examiner Initial | | Document Number | Issue Date | Name | Class | Subci | | Date If |
| | AA | | | | | | | |
| | AB | | | | | | | |
| | AC | _ | | | | | | |
| | AD | | | | | | | |
| | AE | | | | | | | |
| | AF | | | | | | | |
| | AG | | | | | | | · |
| | AH | | | | | | | • |
| | Al | | | | | | | |
| | AJ | | | | | | | |
| | AK | | <u> </u> | | | | | |
| Foreign | n Patent D | Oocuments | | | | | Tra | nslation |
| | | Document Number | Date | Country | Class | Subcl | ass Yes | No |
| | AL | | | | | | | 1 |
| | AM | | | | | | | |
| | AN | | | | | | | |
| | AO | | | | | | | |
| | AP | | | | | | | |
| OTHE | R ART (I | ncluding Author, | Title, Date, | Pertinent Pages, Etc.) | | | | |
| ilel | AR A | A. Braun, "IMA (| Continues Im | portant APC Standards Work, | " Semiconductor | Internationa | l, December 20 | 00 |
| 1 | AS I | Peters, "Yield February 2001 | Management | Motorola and Infineon Impro | ve APC Strategy, | " Semicond | uctor Internatio | nal, |
| ne | AT " | Applied Materia | roundbreakin | Industry with Process Module og Concept," San Francisco (B | Approach for Nau usiness Wire) July | nometer Ger v 16, 2001 | neration Chipm | aking |
| Examiner | WX | 50 | Date Consid | 117316 | | | | |
| *EXAMINER: | Initial if | eference consider | red, whether | or not citation is in conformatis form with your communicat | nce with MPEP 60 | 9; Draw lin | e through citati | on if not |
| CAMBELLEOBNET | | | oopj or ui | | ion to applicant. | | | |

Express Mail Label No.: EL975550394US

Sheet 9 of 10 sheets

| | AP | | |
|-------|-------|---|---|
| OTHER | ART (| Including Author, Title, Date, Pertinent Pages, Etc.) | |
| 2 | | Nanometrics' NanoSpec 9000 Series Integrated Metrology Systems, downloaded from http://www.nanometrics.com/ProductsIntegrated.htm on 9/17/01 | |
| h /. | AS | "Applied Materials Launches Industry's First In-Line Metrology SEM System with 3D Imaging " Jan 10, 2000 | _ |

AT Solid State Technology; Claasen-Vujcic et al; "Aralysis of a 200/300mm Vertical Furnace with Integrated Technology"; April 2001; pps. s6, s8, s12

Examine Date Considered

*EXAMINER: Initial illreference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

downloaded from http://www.semiseek.com/News/press_release55.html

C:\WP51\FORMS\1449.PTO 1/94

| Sheet | 10 | f_2_she | ets | | | | | | | |
|--|--|-----------|--------------------|--------------|---------------------|----------------------|-----------------|---------------------------|-------------|----------|
| U.S. Department of Commerce, Patent and Trademark Office | | | | | | Docket No 6353/P1 | | Serial No.: 10/759,801 | | |
| O BEST OF RELEVANT ART CITED BY APPLICANT | | | | | | Applicants: | | | | |
| (Use several sheets if necessary) | | | | | | Howard Li, et al | | | | |
| ושמן | FEB 17 2023 8 | | | | | Filing Date: Group: | | | | |
| A. | ر. | | | | | Jan | uary 16, 2004 | | 176 | <u>ک</u> |
| U.S. Patent Documents | | | | | | | | | | |
| *Exan | niner | T - | Document | Issue | T | | <u> </u> | <u> </u> | Filing | Date If |
| Init | ial | | Number | Date | Name | | Class | Subclass | Appr | opriate |
| 18 | <u>} </u> | US-1 | 5,408,450 | 04/18/95 | Mozumder et al. | | 364 | 44.12 |) | |
| | | US-2 | 6,004,706 | 12/21/99 | Ausschnitt et al. | | 430 | 30 | | |
| | | US-3 | 6,213,848 B1 | 04/10/01 | Campbell et al. | | 700 | (| | |
| | | US-4 | 6,148,239 | 11/14/00 | Funk et al. | | 451 | 4(| | |
| | | US-5 | 6,304,999 B1 | 10/16/01 | Toprac et al. | | 716 | 4 | | |
| | | US-6 | 6,405,144 B1 | 06/11/02 | Toprac et al. | | 702 | 84 | | |
| | | US-7 | 6,408,220 B1 | 06/18/02 | Nulman | | 700 | 121 | | |
| | | US-8 | 6,454,899 B1 | 09/24/02 | Campbell et al. | | (Yo | 345.2 | 4 | |
| | | US-9 | 6,486,492 B1 | 11/26/02 | Su | | 257 | 48 | | |
| | | US-10 | 6,546,306 B1 | 04/08/03 | Bushman et al. | | 720 | 121 | | |
| | V | US-11 | 6,587,744 B1 | 07/01/03 | Stoddard et al. | - | 700 | 121 | | |
| Foreign Patent Documents Translation | | | | | | | | | | |
| | | | Document Number | Date | Countr | у | Class | Subclass | Yes | No |
| | | F-1 | | - | - | | | | | |
| | - | F-2 | | | | | | | | |
| | | F-3 | | | | | · · | | | |
| | | F-4 | | | | | | | | |
| | | F-5 | | | | | | | | |
| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | | | |
| | | OT-1 | . | | | | | | | .— |
| OT-2 | | | | | | | | | | |
| OT-3 | | | | | | | | | | |
| Examiner Date Considered | | | | | | | | | | |
| *EXAM | IINER | : Initial | f reference cons | idered, whet | her or not citation | s in conform | nance with MPEP | 609; Draw line | through cit | ation if |
| not in conformance and not considered. Include copy of this form with your communication to applicant. | | | | | | | | | | |

C:\WP51\FORM\$\1449.PTO 1/94

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if

C:\WP51\FORMS\1449.PTO 1/94

Examiner/

Express Mail Label No.: EL975550624US

Date Considered

not in conformance and not considered. Include copy of this form with your communication to applicant.